

FW250-TL-E-VB Datasheet Dual N-Channel 60 V (D-S) 175 °C MOSFET

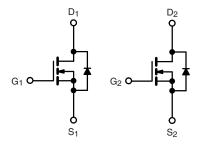
PRODUCT SUMMARY				
V _{DS} (V)	60			
$R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$	0.028			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 V$	0.030			
I _D (A) per leg	7			
Configuration	Dual			

FEATURES

- TrenchFET[®] power MOSFET
- 100 % $\rm R_g$ and UIS tested







N-Channel MOSFET N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	60	V	
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current	T _C = 25 °C	1	7		
Continuous Drain Current	T _C = 125 °C	l _D	4		
Continuous Source Current (Diode Conduction) ^a		I _S	3.6	A	
Pulsed Drain Current ^b		I _{DM}	28		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	18		
Single Pulse Avalanche Energy		E _{AS}	16.2	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	PD	4	W	
	T _C = 125 °C	r D	1.3	٧V	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	С°	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	110	°C/W		
Junction-to-Foot (Drain)		R _{thJF}	34	0/10		

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR4 material).

PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$		60	-	-	V
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$		2.0	2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 V, V_{GS} = \pm 20 V$		-	± 100	nA
		$V_{GS} = 0 V$	V _{DS} = 60 V	-	-	1	μA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	
		$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$	-	-	150	
On-State Drain Current ^a	I _{D(on)}	$V_{GS} = 10 \text{ V}$	$V_{DS} \ge 5 V$	20	-	-	А
		$V_{GS} = 10 V$	I _D = 4.5 A-	-	0.028	-	Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 10 V$	I _D = 4.5 A, T _J = 125 °C	-	0.066	-	
	03(01)	V _{GS} = 10 V	I _D = 4.5 A, T _J = 175 °C	-	0.081	-	
		$V_{GS} = 4.5 V$	I _D = 4 A-	-	0.030	-	
Forward Transconductance ^f	9 _{fs}	V _{DS}	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 4.5 \text{ A}$		15	-	S
Dynamic ^b			•				
Input Capacitance	C _{iss}			-	600	750	
Output Capacitance	Coss	$V_{GS} = 0 V$ $V_{DS} = 25 V, f = 1 MH$	$V_{DS} = 25 V$, f = 1 MHz	-	110	140	pF
Reverse Transfer Capacitance	C _{rss}			-	50	62	
Total Gate Charge ^c	Qg			-	11.7	18	
Gate-Source Charge ^c	Q _{gs}	$V_{GS} = 10 V$	$V_{DS} = 30 \text{ V}, I_D = 5.3 \text{ A}$	-	1.8	2.7	nC
Gate-Drain Charge ^c	Q _{gd}			-	2.8	4.2	
Gate Resistance	Rg		f = 1 MHz		-	6	Ω
Turn-On Delay Time ^c	t _{d(on)}			-	7	11	
Rise Time ^c	t _r	V _{DD} =	$V_{DD} = 30 \text{ V}, \text{ R}_{\text{I}} = 6.8 \Omega$		3.3	5	- ns
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 4.4$ A, $V_{GEN} = 10$ V, $R_g = 1 \Omega$		-	22.4	33.5	
Fall Time ^c	t _f			-	2.1	3.2	
Source-Drain Diode Ratings and Chara	acteristics ^b	<u> </u>					
Pulsed Current ^a	I _{SM}			-	-	28	А
Forward Voltage	V _{SD}	IF =	= 2 A, V _{GS} = 0 V	-	0.75	1.1	V
-	_	1		1	i	I	I

Notes

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

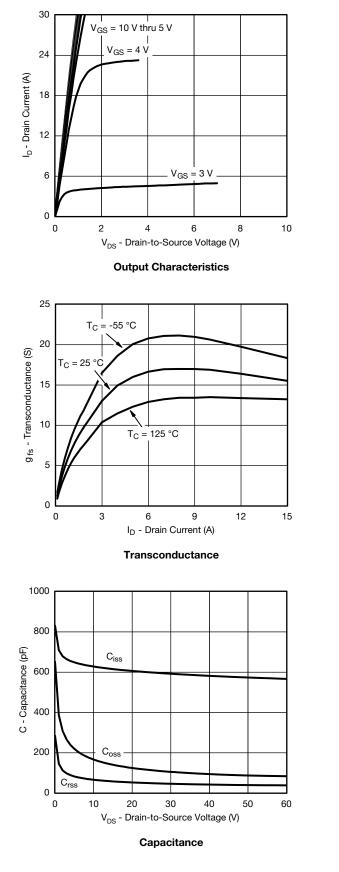
c. Independent of operating temperature.

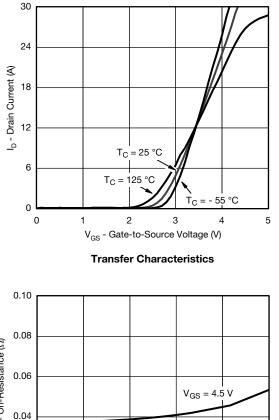
Bsemi

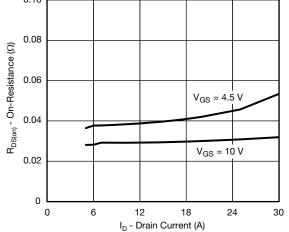
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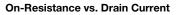


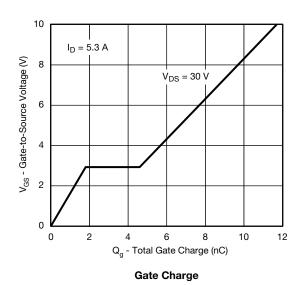
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



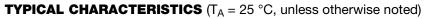


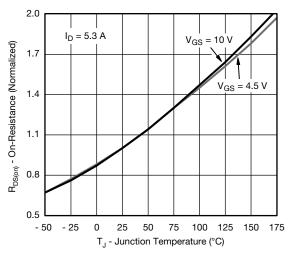




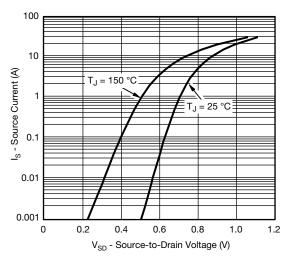




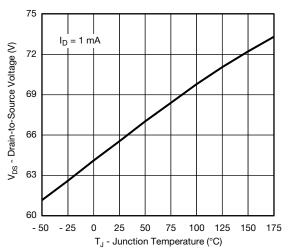




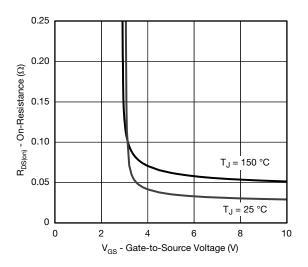
On-Resistance vs. Junction Temperature



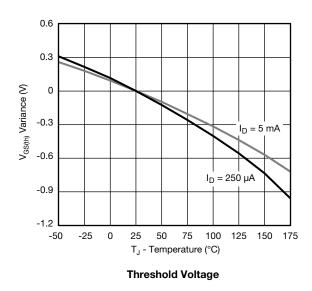
Source Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature

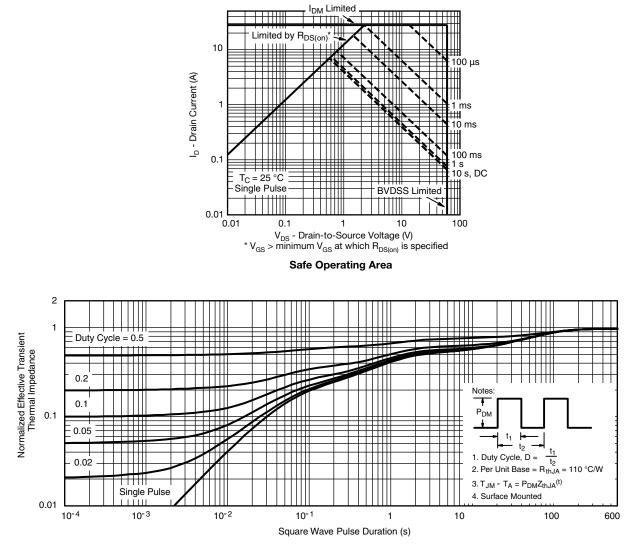


On-Resistance vs. Gate-to-Source Voltage





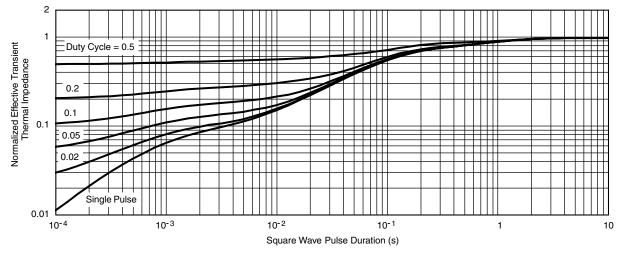
THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)

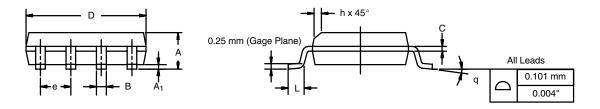


Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012



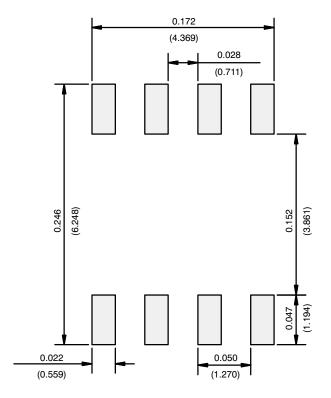


	MILLIM	IETERS	INCHES		
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					

FW250-TL-E-VB



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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